

Handling Precautions

Carefully note the following points when mounting or using these products.

- 1 Do not bend the lead wires, as this may damage them.
- 2 Do not apply a voltage higher than the absolute maximum rated voltage between input and output terminals. This may lead to surges or overvoltage, which could damage the device.
- 3 When mounting the device using adhesives or soldering flux to fasten the terminals, use only highly insulating materials. If insulation becomes poor, the imbalance voltage may be shifted.
- 4 The lead terminals of the Hall IC (see the outline dimensions diagram) are directly connected to the enclosed IC. Be careful not to allow the lead terminals to connect to any other circuit.
- 5 When soldering, be sure to maintain the following conditions
 - (a) Manual soldering (300°C max., 5 seconds or less)

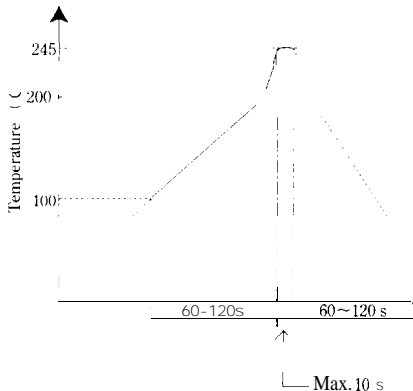
Take care when attaching the device using a soldering iron, since the package can be easily damaged (be especially careful not to place any stress on the lead wire).

If there is a leak in the soldering iron (for example, when the tip of the iron touches a power supply), this may damage the device. Use a soldering iron with little or no leakage.

When repairing, avoid removing and using a device again which was mounted by soldering.

(b) Reflow soldering

- 1) Preheating
100°C to 200°C for 2 minutes,
- 2) Soldering
245°C max. for 10 s max.
- 3) Cooling
Gradual cooling (avoid rapid cooling)



6 Cleaning

(a) Solvents

The resin may be immersed in the solvent, depending on the type of solvent used. Use the following solvents only

- Methyl alcohol
- Ethyl alcohol
- Isopropyl alcohol

Note : When using alternative cleaning materials, the resin may be immersed in the solvent, Carefully check that the cleaning materials are safe before using them,

(b) Cleaning method

Immersion in solvents	Solvent temperature : 45°C or less Immersion time: 3 minutes or less
Ultrasonic	The effect on the device varies according to the size of the cleaning tank, ultrasonic wave output, time, size of the substrate, and the method by which the device was mounted. Try this method beforehand under the actual conditions of use, and proceed with cleaning only if nothing unusual occurs.